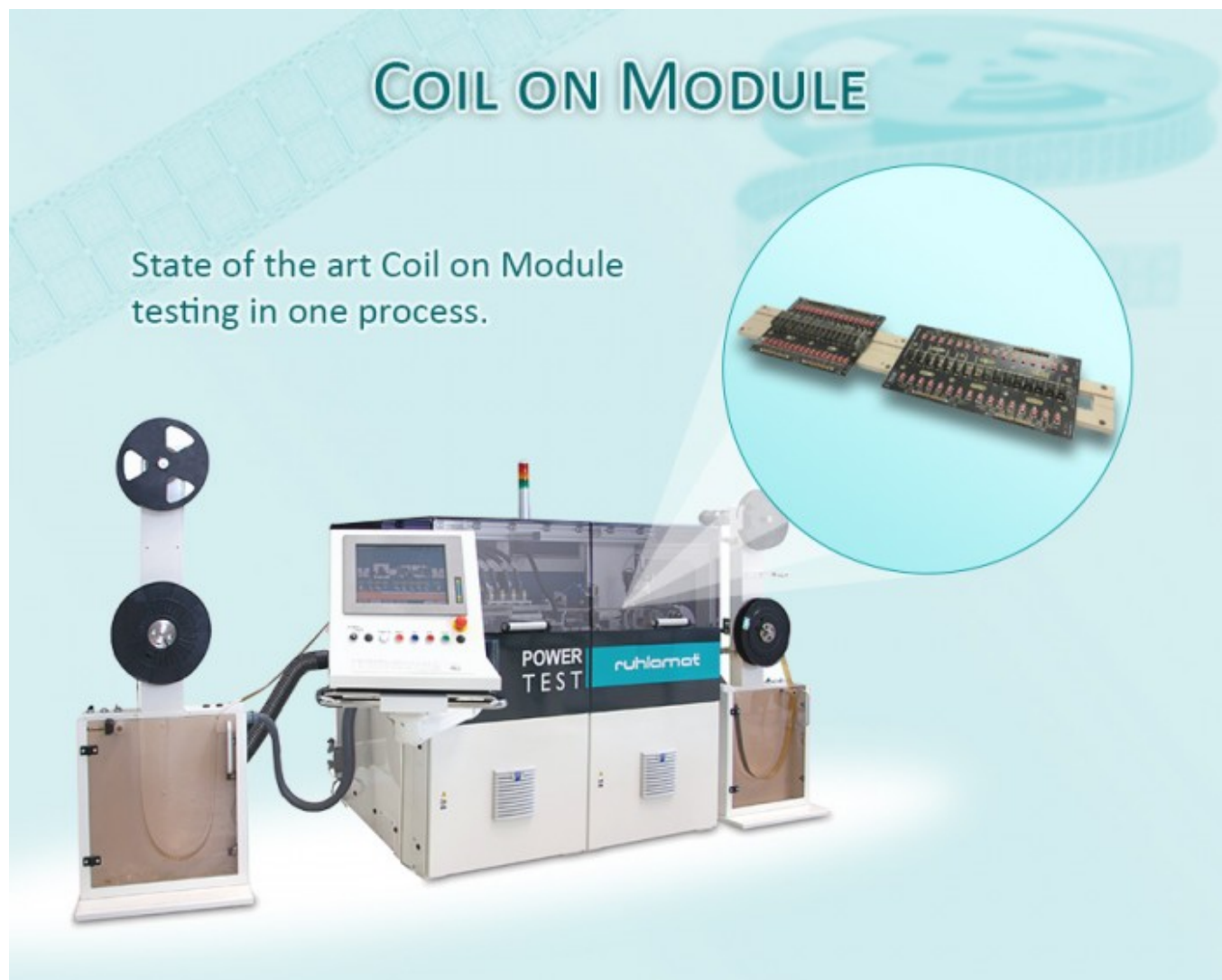


Coil on Module test for PowerTest series available



[1]

January 2020 - Coil on Module (CoM) chip technology for dual interface solutions is becoming increasingly important in smart card manufacturing, especially for the ID, security and banking sectors.

Therefore it is necessary to produce these modules in high quantities and of high quality. For outgoing goods inspection and incoming goods inspection, solutions for testing and initialization are required. The technology portfolio of the module tester series [PowerTest](#) [2] was extended by this technology. Based on the CoM test solution of our partner Smartware, there is now a station available for a functional test and for initializing or personalizing CoM modules directly in the module belt.

Test boards for modular belts with a width of 35mm and a pitch of 9.5mm or 14.25mm are available. In the basic version 32 modules can be tested in parallel. The additional test boards use the AC2 outputs of the existing test hardware (US-CLT) on a conventional dual interface module tester. This provides a cost-effective solution for all Dual Interface module types. Depending on the configuration of an existing module tester a simple extension is possible.

Source URL: <https://www.ruhlatmat.com/en/company/news/coil-module-test-powertest-series-available>

Links

[1] https://www.ruhlatmat.com/sites/default/files/images/news/com_powertest3.jpg

[2] <https://www.ruhlatmat.com/en/card-systems-and-passport-systems/chip-module-production/chip-module-test-system>